

Final Product/Process Change Notification Document #:FPCN25425XA Issue Date:09 Sep 2024

Title of Change:	Assembly material change of 1.0mil gold wire to 1.0mil palladium coated copper for SSOT6 Analog package in onsemi Cebu, Philippines.			
Proposed First Ship date:	16 Dec 2024 or earlier if approved by customer			
Contact Information:	Contact your local onsemi Sales Office or <u>Ernesto.Villamor@onsemi.com or</u> Joseph.Mendoza@onsemi.com			
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.			
Additional Reliability Data:	Contact your local	Contact your local onsemi Sales Office or <u>Aileen.Allado@onsemi.com</u>		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <u>PCN.Support@onsemi.com</u>			
Marking of Parts/ Traceability of Change:	Identification through date code cut off.			
Change Category:	Assembly Change			
Change Sub-Category(s):	Material Change			
Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
onsemi Sites onsemi Cebu, Philippines		External Foundry/Subcon Sites None		
onsemi Sites onsemi Cebu, Philippines Description and Purpose: onsemi has completed qualification of PCC wi		None Package identified in this notification.		
onsemi Sites onsemi Cebu, Philippines Description and Purpose: onsemi has completed qualification of PCC wi		None Package identified in this notification.	То	
onsemi Sites onsemi Cebu, Philippines Description and Purpose: onsemi has completed qualification of PCC wi	dize the bonding wire	None backage identified in this notification. e used for SSOT6 analog package.	To 1.0 mil PCC wir	re
onsemi Sites onsemi Cebu, Philippines Description and Purpose: onsemi has completed qualification of PCC wi This change is being made in order to standar Bond Wire There is no product marking change as a resul Reliability Data Summary: QV DEVICE NAME: FAN5622SX RMS: F91436	dize the bonding wire 1.	None Package identified in this notification. Package for SSOT6 analog package. From From	-	e
Description and Purpose: Description and Purpo	dize the bonding wire 1. It of this change.	None Package identified in this notification. Package identified in this notif	1.0 mil PCC wir	-
Description and Purpose: Description and Pu	dize the bonding wire 1. It of this change. BF Specification	None backage identified in this notification. e used for SSOT6 analog package. From 0 mil Au wire	1.0 mil PCC wir	Results
onsemi Sites onsemi Cebu, Philippines Description and Purpose: onsemi has completed qualification of PCC wi This change is being made in order to standar Bond Wire There is no product marking change as a resul Reliability Data Summary: QV DEVICE NAME: FAN5622SX RMS: F91436 PACKAGE: F369 TSOT-23 6L AU SNGL HPE	dize the bonding wire 1. It of this change.	None backage identified in this notification. e used for SSOT6 analog package. From 0 mil Au wire 0 mil Au wire Condition Ta= 150°C MSL 1 @ 260 °C, Pre TC, uHAST, HAST for	1.0 mil PCC wir	-
Description and Purpose: Description: Bond Wire Fhere is no product marking change as a result Reliability Data Summary: QV DEVICE NAME: FAN5622SX RMS: F91436 PACKAGE: F369 TSOT-23 6L AU SNGL HPE Test High Temperature Storage Life	dize the bonding wire 1. It of this change. BF Specification JESD22-A103 J-STD-020 JESD-	None backage identified in this notification. e used for SSOT6 analog package. From 0 mil Au wire O mil Au wire Condition Ta= 150°C	1.0 mil PCC wir	Results 0/231
Description and Purpose: Bond Wire Fhere is no product marking change as a result Reliability Data Summary: QV DEVICE NAME: FAN5622SX RMS: F91436 PACKAGE: F369 TSOT-23 6L AU SNGL HPE Test High Temperature Storage Life Preconditioning	dize the bonding wire 1. It of this change. BF Specification JESD22-A103 J-STD-020 JESD- A113	None backage identified in this notification. e used for SSOT6 analog package. From .0 mil Au wire	1.0 mil PCC wir Interval 1008 hrs	Results 0/231 0/693



Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FAN5622SX	FAN5622SX